

Alloyed 2N Copper Wire for Bonding in Microelectronics Device

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ABSTRACT

An alloyed 2N copper wire for bonding in microelectronics comprising one or more of a group of Ag, Ni, Pd, Au, Pt, and Cr as corrosion resistance alloying material, wherein a concentration of said corrosion resistance alloying material is between about 0.009wt% and about 0.99wt%.

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FIG. 1

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